

HD74LS07

Hex Buffers / Drivers
(With Open Collector High-Voltage Outputs)

REJ03D0393-0200

Rev.2.00

Feb.18.2005

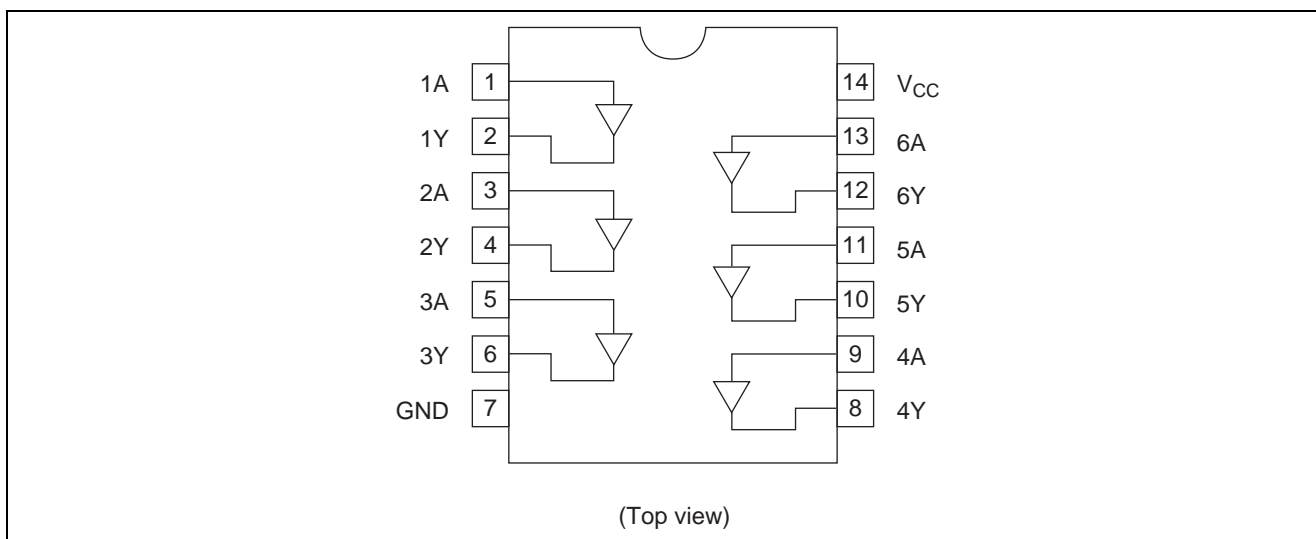
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS07P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS07FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC} ^{Note}	7	V
Input voltage	V_{IN}	7	V
Output voltage	V_{OUT}	30	V
Power dissipation	P_T	400	mW
Storage temperature	T_{stg}	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output voltage	V_{OH}	—	—	30	V
Output current	I_{OL}	—	—	48	mA
Operating temperature	T_{opr}	-20	25	75	°C

Electrical Characteristics

(Ta = -20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V_{IH}	2.0	—	—	V	
	V_{IL}	—	—	0.8	V	
Output voltage	V_{OL}	—	—	0.4	V	$I_{OL} = 24 \text{ mA}$ $V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}$
		—	—	0.5		
Input current	I_{IH}	—	—	20	μA	$V_{CC} = 5.25 \text{ V}, V_I = 2.7 \text{ V}$
	I_{IL}	—	—	-0.4	mA	$V_{CC} = 5.25 \text{ V}, V_I = 0.4 \text{ V}$
	I_I	—	—	0.1	mA	$V_{CC} = 5.25 \text{ V}, V_I = 7 \text{ V}$
Output current	I_{OH}	—	—	250	μA	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{OH} = 30 \text{ V}$
Supply current	I_{CCH}	—	22	41	mA	$V_{CC} = 5.25 \text{ V}$
	I_{CCL}	—	17	30	mA	$V_{CC} = 5.25 \text{ V}$
Input clamp voltage	V_{IK}	—	—	-1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$

Note: * $V_{CC} = 5 \text{ V}, T_a = 25^\circ\text{C}$

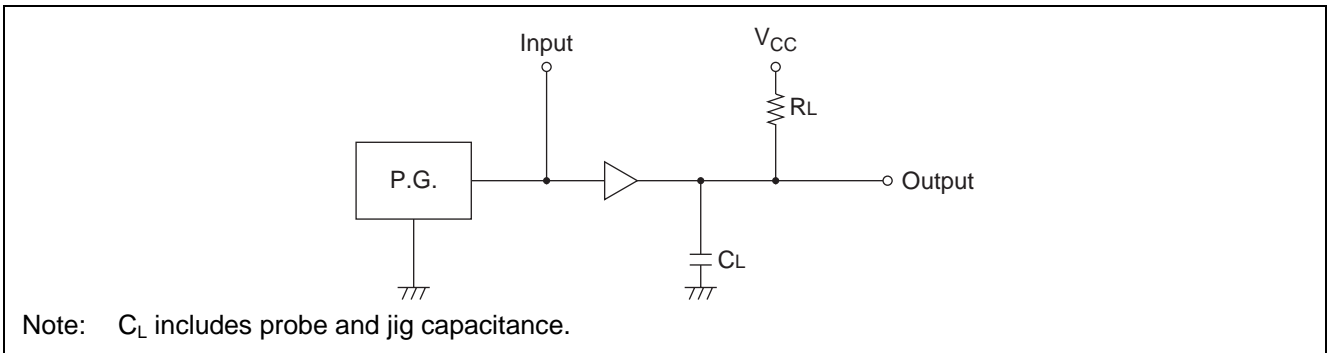
Switching Characteristics

(V_{CC} = 5 V, Ta = 25°C)

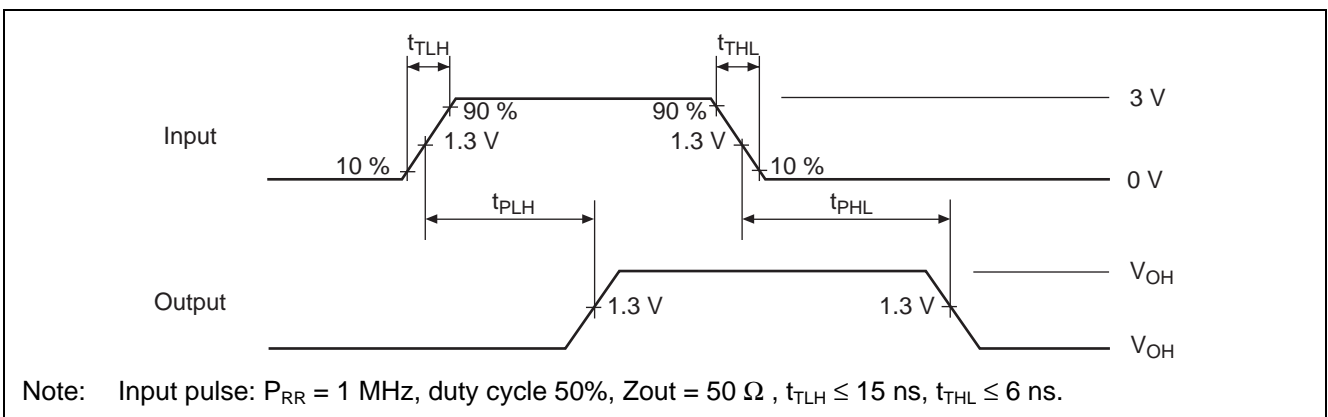
Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t_{PLH}	—	10	15	ns	$C_L = 15 \text{ pF}, R_L = 100 \Omega$
	t_{PHL}	—	20	30	ns	

Testing Method

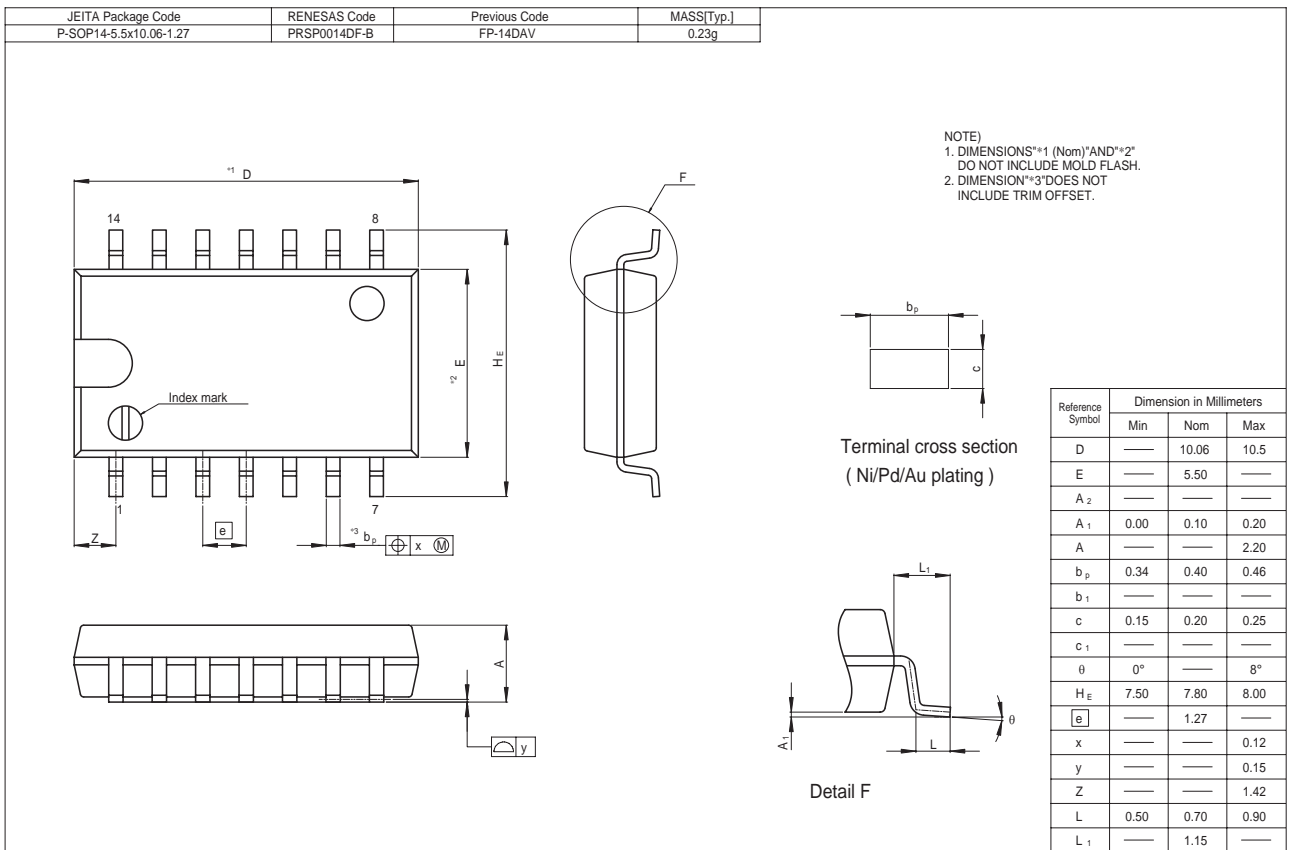
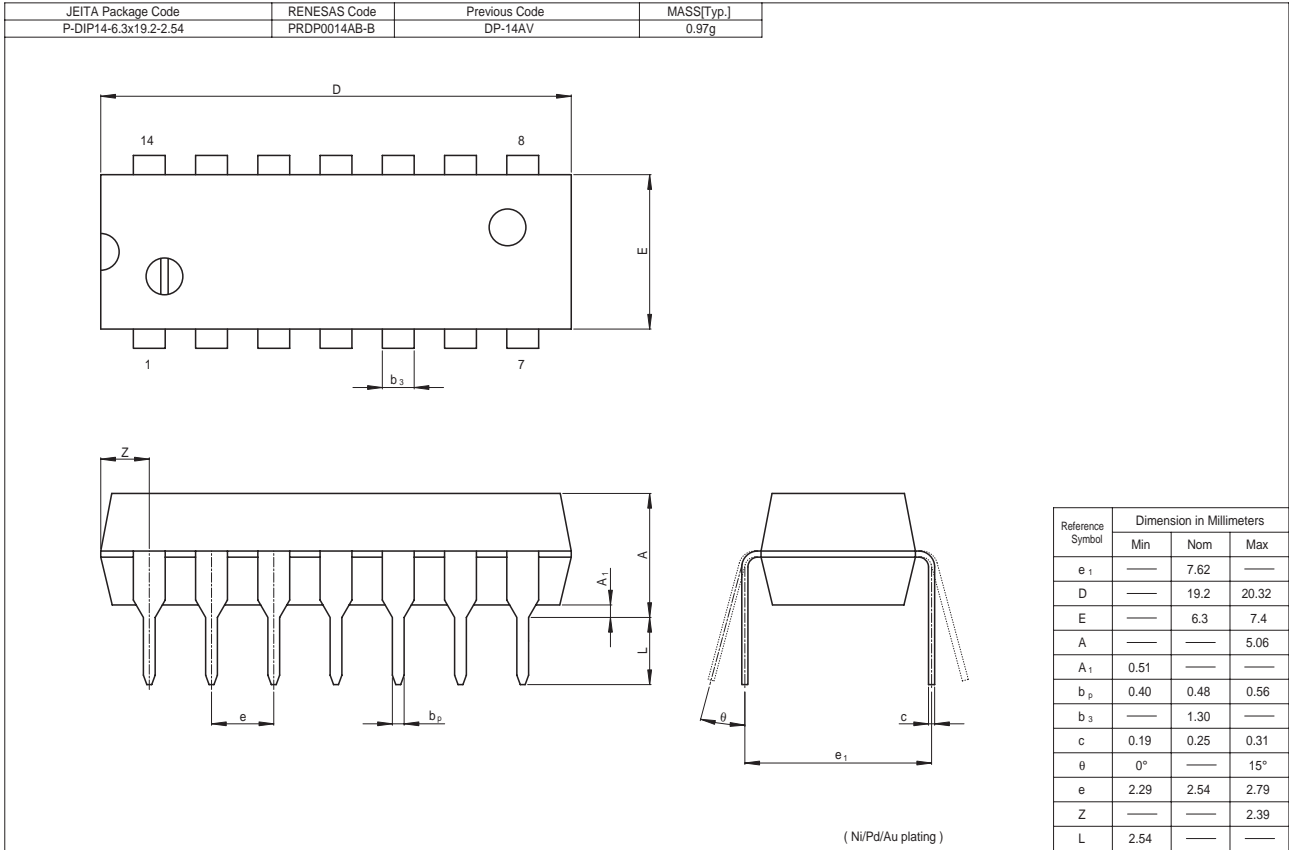
Test Circuit



Waveform



Package Dimensions



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Renesas Technology America, Inc.

450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd.

7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.

10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd.

Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001